

AMENDMENTS TO THE DRAWINGS:

The attached sheets of drawings include changes to Figs. 1, 5, 13A, and 13B.

The reference to 14 has been deleted from Figure 1.

Applicant has modified Figure 5 to include the reference to 8x. Applicant has also modified the reference designator 6A in Figure 5 to be consistent with the wafer designated 6 in Figure 1.

Applicant has amended Figures 13A and 13B to reference items 31 and 35. The reference to 37 has been deleted from Figs. 13A and 13B.

Attachment: Replacement Sheets

Annotated Sheets Showing Changes

REMARKS

Applicant thanks the Examiner for acknowledging receipt of Applicants foreign priority document that has been submitted pursuant to 35 U.S.C. §119.

In regard to the drawing objections, Applicant has modified Figure 5 to include the reference to 8x. Additionally, Applicant has amended Figs. 13A and 13 B to reference items 31 and 35. In regard to the objections to the drawings set forth in paragraph 2, Applicant has modified the reference designator 6A in Figure 5 to be consistent with the wafer designated 6 in Figure 1. The reference to 37 has been deleted from Figs. 13A and 13B, and the reference to 14 has been deleted from Figure 1. Applicant submits that these modifications obviate the Examiners objections to the drawings. Accordingly, Applicants requests these objections now be withdrawn.

Applicant has also modified the Specification in accordance with the Examiners suggestions. Applicant respectfully requests reconsideration of the rejections set forth by the Examiner under 35 U.S.C. §112. Applicant has modified the claims in order to overcome these rejections, and accordingly, Applicant requests that the objections be withdrawn.

Applicant respectfully requests reconsideration of the prior art rejections set forth by the Examiner under 35 U.S.C. §§102 and 103. Applicant submits that the prior art references of record, whether considered alone, or in combination, fail to either teach or suggest the presently claimed invention. More specifically, Applicant has modified Claim 1 to further specify that: "wherein the mask correction units are comprised of a plurality of individual

correction values each of which correspond to a location having a desired line width for each of a plurality of lines."

The prior art of record provides no teaching or suggestion whatsoever regarding correction of photomask data as specified in the instant application . Applicant notes that the *Chen* reference, U.S. Patent No. 5,707,765 is merely directed to a photolithography technique which makes corrections using serifs. Serifs are designed for the purpose of overcoming the problem of corner rounding during semiconductor circuit fabrication in order to improves the correspondence between the original circuit design and the layout at corners. The technique described in the reference is thus merely directed to providing a more accurate photomask through correcting corner regions exclusively. See specifically column 3 at lines 59-67. Applicants instant invention is a substantial improvement and may be used to correct the photomask at a variety of locations for a plurality of individual lines. See specifically Figs. 2 and 3.

In light of the foregoing, Applicant respectfully requests the rejections be withdrawn.

Respectfully submitted,

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